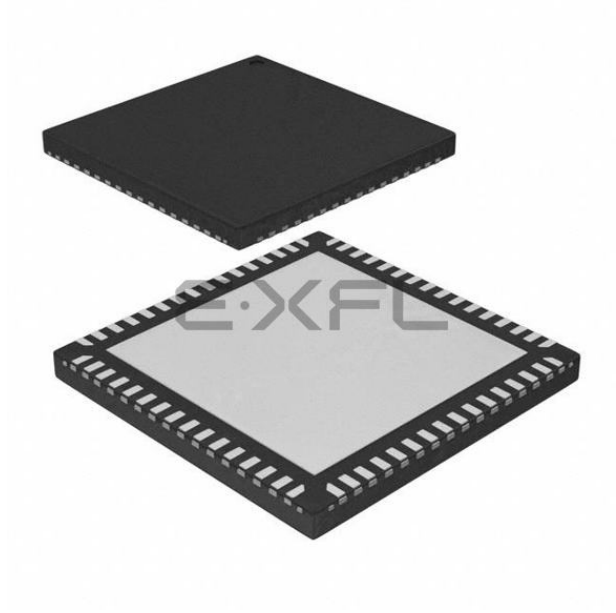
# Silicon Labs - EFM32WG330F128-QFN64T Datasheet



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## What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

## Applications of "Embedded - Microcontrollers"

| Details | |
|---|---|
| Product Status | Discontinued at Digi-Key |
| Core Processor | ARM® Cortex®-M4F |
| Core Size | 32-Bit Single-Core |
| Speed | 48MHz |
| Connectivity | I²C, IrDA, SmartCard, SPI, UART/USART, USB |
| Peripherals | Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT |
| Number of I/O | 52 |
| Program Memory Size | 128KB (128K x 8) |
| Program Memory Type | FLASH |
| EEPROM Size | - |
| RAM Size | 32K x 8 |
| Voltage - Supply (Vcc/Vdd) | 1.98V ~ 3.8V |
| Data Converters | A/D 8x12b; D/A 2x12b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 85°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 64-VFQFN Exposed Pad |
| Supplier Device Package | 64-QFN (9x9) |
| Purchase URL | https://www.e-xfl.com/product-detail/silicon-labs/efm32wg330f128-qfn64t |

### 2.1.3 Memory System Controller (MSC)

The Memory System Controller (MSC) is the program memory unit of the EFM32WG microcontroller. The flash memory is readable and writable from both the Cortex-M4 and DMA. The flash memory is divided into two blocks; the main block and the information block. Program code is normally written to the main block. Additionally, the information block is available for special user data and flash lock bits. There is also a read-only page in the information block containing system and device calibration data. Read and write operations are supported in the energy modes EM0 and EM1.

### 2.1.4 Direct Memory Access Controller (DMA)

The Direct Memory Access (DMA) controller performs memory operations independently of the CPU. This has the benefit of reducing the energy consumption and the workload of the CPU, and enables the system to stay in low energy modes when moving for instance data from the USART to RAM or from the External Bus Interface to a PWM-generating timer. The DMA controller uses the PL230 µDMA controller licensed from ARM.

### 2.1.5 Reset Management Unit (RMU)

The RMU is responsible for handling the reset functionality of the EFM32WG.

### 2.1.6 Energy Management Unit (EMU)

The Energy Management Unit (EMU) manage all the low energy modes (EM) in EFM32WG microcontrollers. Each energy mode manages if the CPU and the various peripherals are available. The EMU can also be used to turn off the power to unused SRAM blocks.

### 2.1.7 Clock Management Unit (CMU)

The Clock Management Unit (CMU) is responsible for controlling the oscillators and clocks on-board the EFM32WG. The CMU provides the capability to turn on and off the clock on an individual basis to all peripheral modules in addition to enable/disable and configure the available oscillators. The high degree of flexibility enables software to minimize energy consumption in any specific application by not wasting power on peripherals and oscillators that are inactive.

### 2.1.8 Watchdog (WDOG)

The purpose of the watchdog timer is to generate a reset in case of a system failure, to increase application reliability. The failure may e.g. be caused by an external event, such as an ESD pulse, or by a software failure.

### 2.1.9 Peripheral Reflex System (PRS)

The Peripheral Reflex System (PRS) system is a network which lets the different peripheral module communicate directly with each other without involving the CPU. Peripheral modules which send out Reflex signals are called producers. The PRS routes these reflex signals to consumer peripherals which apply actions depending on the data received. The format for the Reflex signals is not given, but edge triggers and other functionality can be applied by the PRS.

### 2.1.10 Universal Serial Bus Controller (USB)

The USB is a full-speed USB 2.0 compliant OTG host/device controller. The USB can be used in Device, On-the-go (OTG) Dual Role Device or Host-only configuration. In OTG mode the USB supports both Host Negotiation Protocol (HNP) and Session Request Protocol (SRP). The device supports both full-speed (12MBit/s) and low speed (1.5MBit/s) operation. The USB device includes an internal dedicated

available in energy mode EM2, in addition to EM0 and EM1, making it ideal for sensor monitoring in applications with a strict energy budget.

### 2.1.26 Backup Power Domain

The backup power domain is a separate power domain containing a Backup Real Time Counter, BURTC, and a set of retention registers, available in all energy modes. This power domain can be configured to automatically change power source to a backup battery when the main power drains out. The backup power domain enables the EFM32WG330 to keep track of time and retain data, even if the main power source should drain out.

### 2.1.27 Advanced Encryption Standard Accelerator (AES)

The AES accelerator performs AES encryption and decryption with 128-bit or 256-bit keys. Encrypting or decrypting one 128-bit data block takes 52 HFCORECLK cycles with 128-bit keys and 75 HFCORECLK cycles with 256-bit keys. The AES module is an AHB slave which enables efficient access to the data and key registers. All write accesses to the AES module must be 32-bit operations, i.e. 8- or 16-bit operations are not supported.

### 2.1.28 General Purpose Input/Output (GPIO)

In the EFM32WG330, there are 52 General Purpose Input/Output (GPIO) pins, which are divided into ports with up to 16 pins each. These pins can individually be configured as either an output or input. More advanced configurations like open-drain, filtering and drive strength can also be configured individually for the pins. The GPIO pins can also be overridden by peripheral pin connections, like Timer PWM outputs or USART communication, which can be routed to several locations on the device. The GPIO supports up to 16 asynchronous external pin interrupts, which enables interrupts from any pin on the device. Also, the input value of a pin can be routed through the Peripheral Reflex System to other peripherals.

## 2.2 Configuration Summary

The features of the EFM32WG330 is a subset of the feature set described in the EFM32WG Reference Manual. Table 2.1 (p. 7) describes device specific implementation of the features.

***Table 2.1. Configuration Summary***

| Module | Configuration | Pin Connections |
|---|---|---|
| Cortex-M4 | Full configuration | NA |
| DBG | Full configuration | DBG_SWCLK, DBG_SWDIO, DBG_SWO |
| MSC | Full configuration | NA |
| DMA | Full configuration | NA |
| RMU | Full configuration | NA |
| EMU | Full configuration | NA |
| CMU | Full configuration | CMU_OUT0, CMU_OUT1 |
| WDOG | Full configuration | NA |
| PRS | Full configuration | NA |
| USB | Full configuration | USB_VBUS, USB_VBUSEN, USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP, USB_ID |

# 3 Electrical Characteristics

## 3.1 Test Conditions

### 3.1.1 Typical Values

The typical data are based on $T_{AMB}$=25°C and $V_{DD}$=3.0 V, as defined in Table 3.2 (p. 10), by simulation and/or technology characterisation unless otherwise specified.

### 3.1.2 Minimum and Maximum Values

The minimum and maximum values represent the worst conditions of ambient temperature, supply voltage and frequencies, as defined in Table 3.2 (p. 10), by simulation and/or technology characterisation unless otherwise specified.

## 3.2 Absolute Maximum Ratings

The absolute maximum ratings are stress ratings, and functional operation under such conditions are not guaranteed. Stress beyond the limits specified in Table 3.1 (p. 10) may affect the device reliability or cause permanent damage to the device. Functional operating conditions are given in Table 3.2 (p. 10) .

***Table 3.1. Absolute Maximum Ratings***

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $T_{STG}$ | Storage temperature range | | -40 | | 150[1] | °C |
| $T_S$ | Maximum soldering temperature | Latest IPC/JEDEC J-STD-020 Standard | | | 260 | °C |
| $V_{DDMAX}$ | External main supply voltage | | 0 | | 3.8 | V |
| $V_{IOPIN}$ | Voltage on any I/O pin | | -0.3 | | $V_{DD}$+0.3 | V |

[1]Based on programmed devices tested for 10000 hours at 150ºC. Storage temperature affects retention of preprogrammed calibration values stored in flash. Please refer to the Flash section in the Electrical Characteristics for information on flash data retention for different temperatures.

## 3.3 General Operating Conditions

### 3.3.1 General Operating Conditions

***Table 3.2. General Operating Conditions***

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $T_{AMB}$ | Ambient temperature range | -40 | | 85 | °C |
| $V_{DDOP}$ | Operating supply voltage | 1.98 | | 3.8 | V |
| $f_{APB}$ | Internal APB clock frequency | | | 48 | MHz |
| $f_{AHB}$ | Internal AHB clock frequency | | | 48 | MHz |

## 3.7 Flash

***Table 3.7. Flash***

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $EC_{FLASH}$ | Flash erase cycles before failure | | 20000 | | | cycles |
| $RET_{FLASH}$ | Flash data retention | $T_{AMB}$<150°C | 10000 | | | h |
| | | $T_{AMB}$<85°C | 10 | | | years |
| | | $T_{AMB}$<70°C | 20 | | | years |
| $t_{W\_PROG}$ | Word (32-bit) programming time | | 20 | | | µs |
| $t_{PERASE}$ | Page erase time | | 20 | 20.4 | 20.8 | ms |
| $t_{DERASE}$ | Device erase time | | 40 | 40.8 | 41.6 | ms |
| $I_{ERASE}$ | Erase current | | | | 7[1] | mA |
| $I_{WRITE}$ | Write current | | | | 7[1] | mA |
| $V_{FLASH}$ | Supply voltage during flash erase and write | | 1.98 | | 3.8 | V |

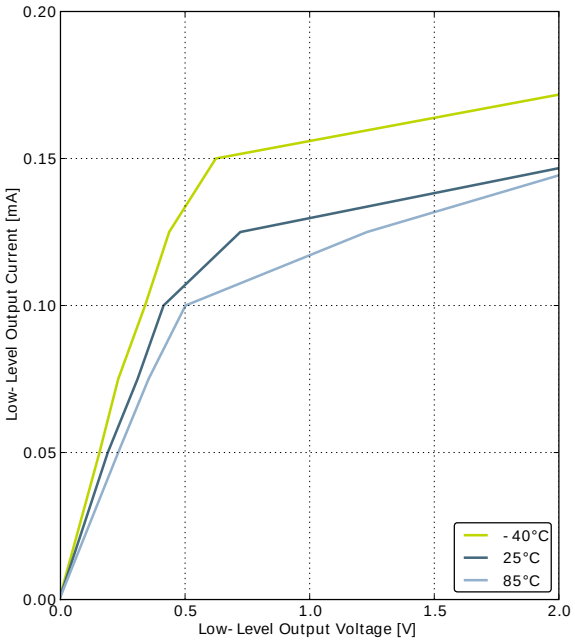
[1]Measured at 25°C

## 3.8 General Purpose Input Output

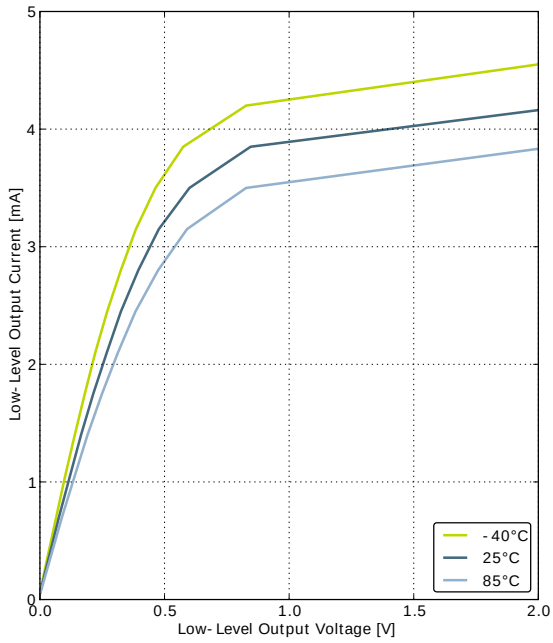
***Table 3.8. GPIO***

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{IOIL}$ | Input low voltage | | | | $0.30V_{DD}$ | V |
| $V_{IOIH}$ | Input high voltage | | $0.70V_{DD}$ | | | V |
| $V_{IOOH}$ | Output high voltage (Production test condition = 3.0V, DRIVEMODE = STANDARD) | Sourcing 0.1 mA, $V_{DD}$=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOWEST | | $0.80V_{DD}$ | | V |
| | | Sourcing 0.1 mA, $V_{DD}$=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOWEST | | $0.90V_{DD}$ | | V |
| | | Sourcing 1 mA, $V_{DD}$=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOW | | $0.85V_{DD}$ | | V |
| | | Sourcing 1 mA, $V_{DD}$=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOW | | $0.90V_{DD}$ | | V |
| | | Sourcing 6 mA, $V_{DD}$=1.98 V, GPIO_Px_CTRL DRIVEMODE = STANDARD | $0.75V_{DD}$ | | | V |
| | | Sourcing 6 mA, $V_{DD}$=3.0 V, GPIO_Px_CTRL DRIVEMODE = STANDARD | $0.85V_{DD}$ | | | V |
| | | Sourcing 20 mA, $V_{DD}$=1.98 V, GPIO_Px_CTRL DRIVEMODE = HIGH | $0.60V_{DD}$ | | | V |

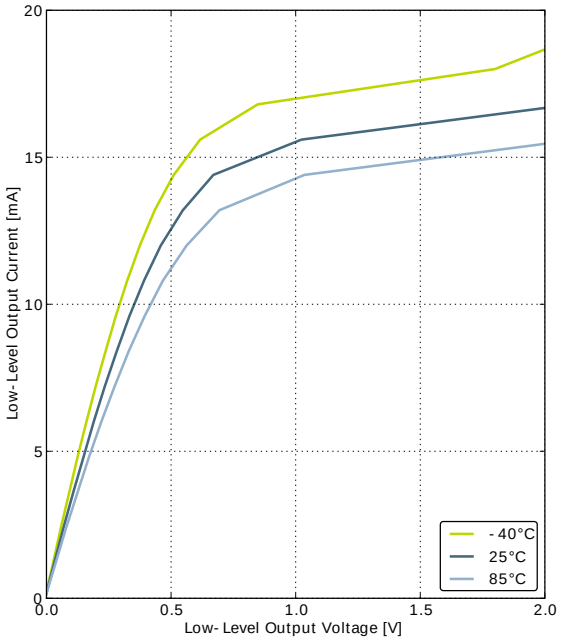
***Figure 3.11. Typical Low-Level Output Current, 2V Supply Voltage***



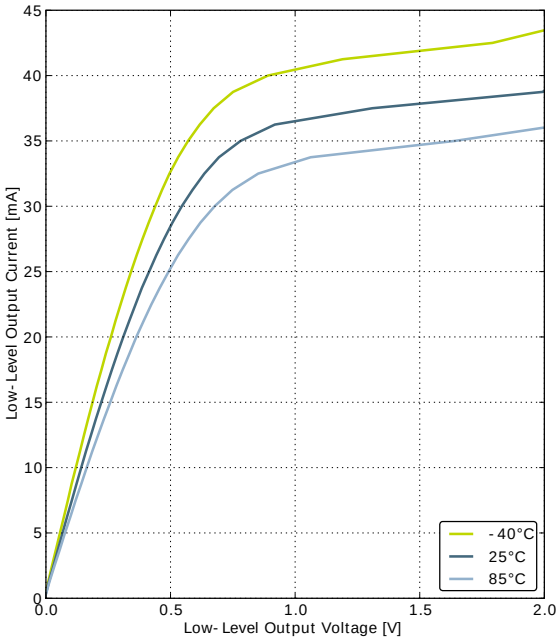

GPIO_Px_CTRL DRIVEMODE = LOWEST




GPIO_Px_CTRL DRIVEMODE = LOW

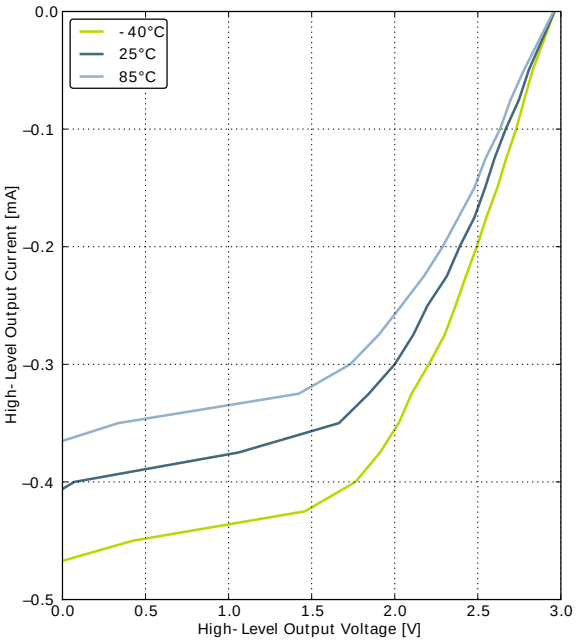



GPIO_Px_CTRL DRIVEMODE = STANDARD

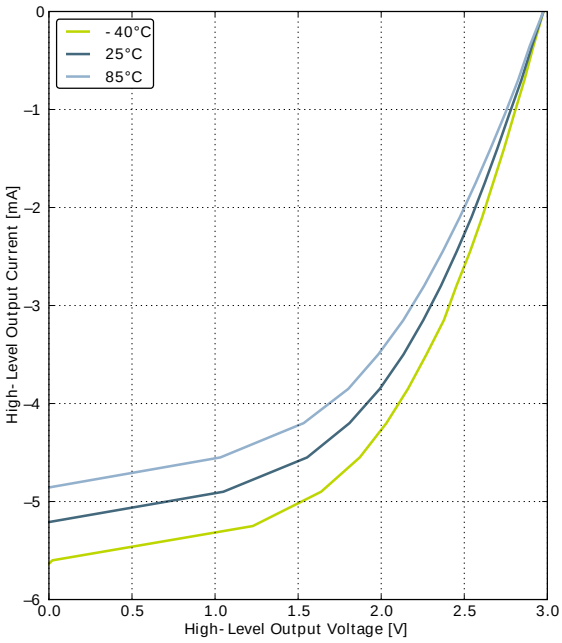



GPIO_Px_CTRL DRIVEMODE = HIGH

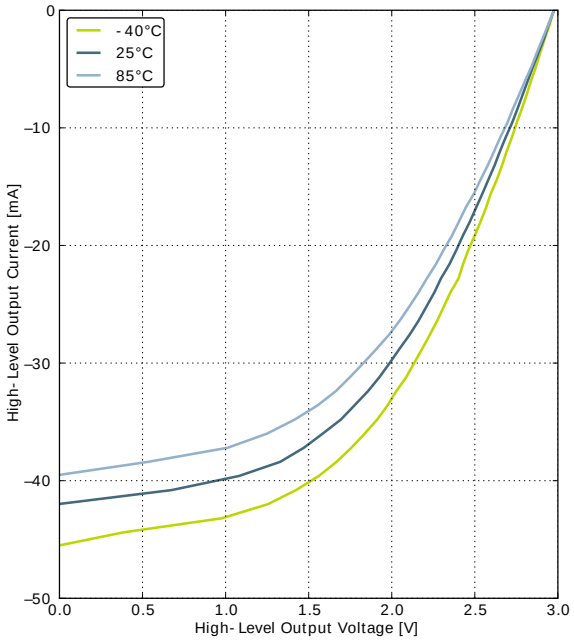
***Figure 3.14. Typical High-Level Output Current, 3V Supply Voltage***



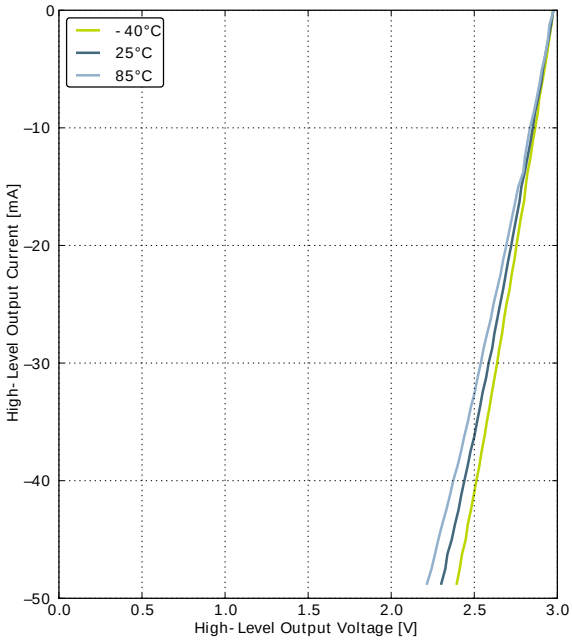

GPIO_Px_CTRL DRIVEMODE = LOWEST




GPIO_Px_CTRL DRIVEMODE = LOW

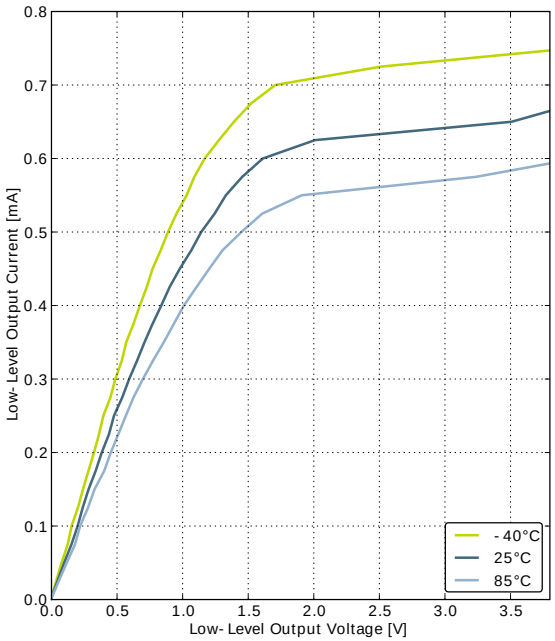



GPIO_Px_CTRL DRIVEMODE = STANDARD

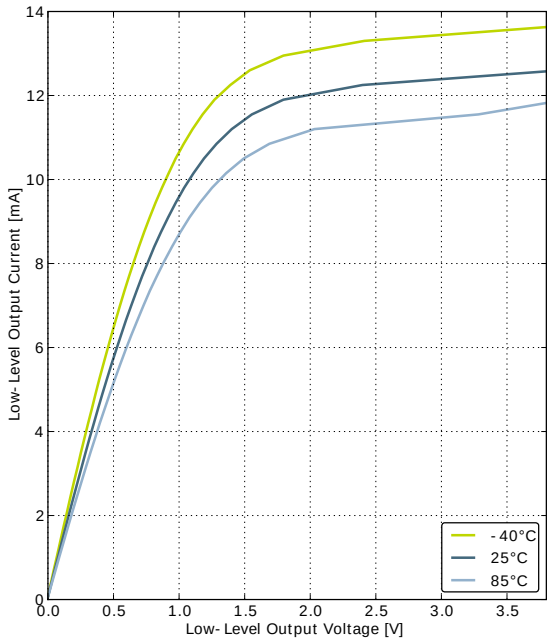



GPIO_Px_CTRL DRIVEMODE = HIGH

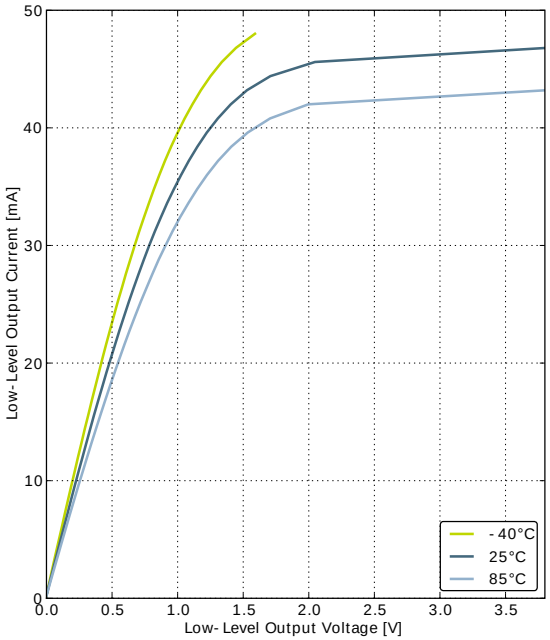
***Figure 3.15. Typical Low-Level Output Current, 3.8V Supply Voltage***



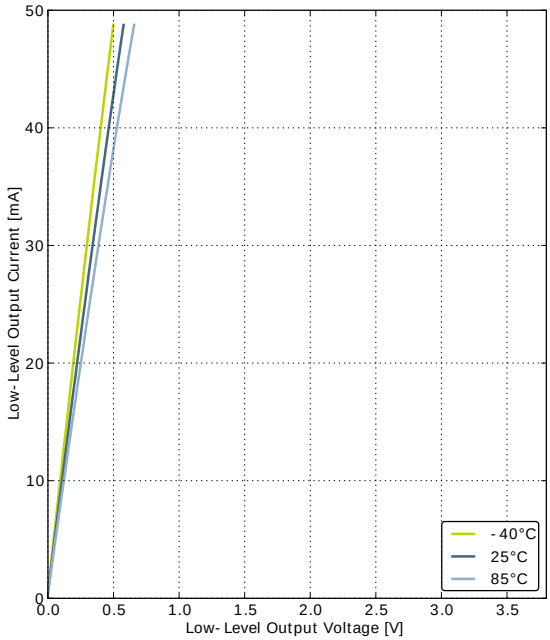

GPIO_Px_CTRL DRIVEMODE = LOWEST




GPIO_Px_CTRL DRIVEMODE = LOW




GPIO_Px_CTRL DRIVEMODE = STANDARD




GPIO_Px_CTRL DRIVEMODE = HIGH

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| | | 200 kSamples/s, 12 bit, differential, internal 1.25V reference | | 79 | | dBc |
| | | 200 kSamples/s, 12 bit, differential, internal 2.5V reference | | 79 | | dBc |
| | | 200 kSamples/s, 12 bit, differential, 5V reference | | 78 | | dBc |
| | | 200 kSamples/s, 12 bit, differential, $V_{DD}$ reference | 68 | 79 | | dBc |
| | | 200 kSamples/s, 12 bit, differential, 2x$V_{DD}$ reference | | 79 | | dBc |
| $V_{ADCOFFSET}$ | Offset voltage | After calibration, single ended | -3.5 | 0.3 | 3 | mV |
| | | After calibration, differential | | 0.3 | | mV |
| $TGRAD_{ADCTH}$ | Thermometer output gradient | | | -1.92 | | mV/°C |
| | | | | -6.3 | | ADC Codes/°C |
| $DNL_{ADC}$ | Differential non-linearity (DNL) | | -1 | ±0.7 | 4 | LSB |
| $INL_{ADC}$ | Integral non-linearity (INL), End point method | | | ±1.2 | ±3 | LSB |
| $MC_{ADC}$ | No missing codes | | 11.999[1] | 12 | | bits |
| $GAIN_{ED}$ | Gain error drift | 1.25V reference | | 0.01[2] | 0.033[3] | %/°C |
| | | 2.5V reference | | 0.01[2] | 0.03[3] | %/°C |
| $OFFSET_{ED}$ | Offset error drift | 1.25V reference | | 0.2[2] | 0.7[3] | LSB/°C |
| | | 2.5V reference | | 0.2[2] | 0.62[3] | LSB/°C |

[1]On the average every ADC will have one missing code, most likely to appear around 2048 +/- n*512 where n can be a value in the set {-3, -2, -1, 1, 2, 3}. There will be no missing code around 2048, and in spite of the missing code the ADC will be monotonic at all times so that a response to a slowly increasing input will always be a slowly increasing output. Around the one code that is missing, the neighbour codes will look wider in the DNL plot. The spectra will show spurs on the level of -78dBc for a full scale input for chips that have the missing code issue.

[2]Typical numbers given by abs(Mean) / (85 - 25).

[3]Max number given by (abs(Mean) + 3x stddev) / (85 - 25).

The integral non-linearity (INL) and differential non-linearity parameters are explained in Figure 3.24 (p. 37) and Figure 3.25 (p. 37) , respectively.

***Figure 3.24. Integral Non-Linearity (INL)***

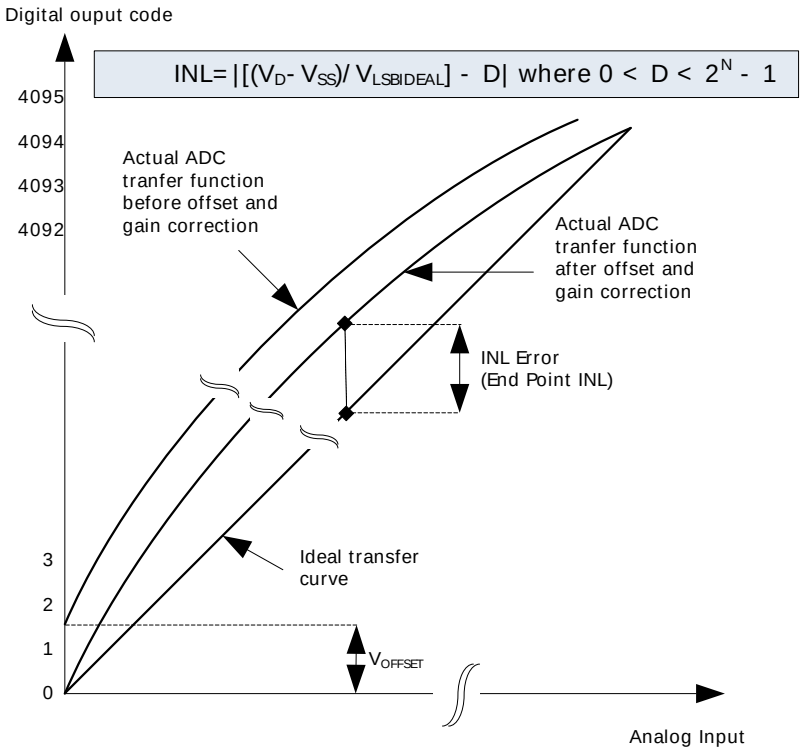
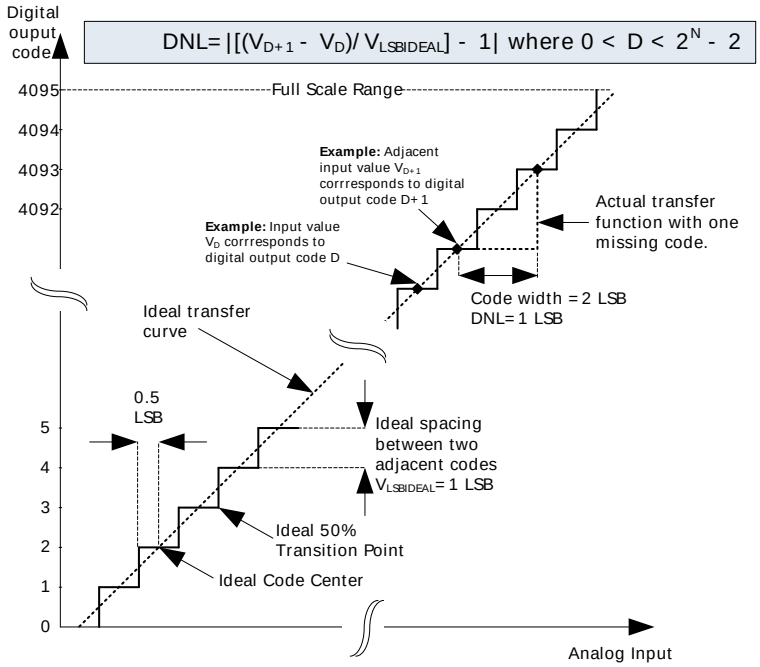
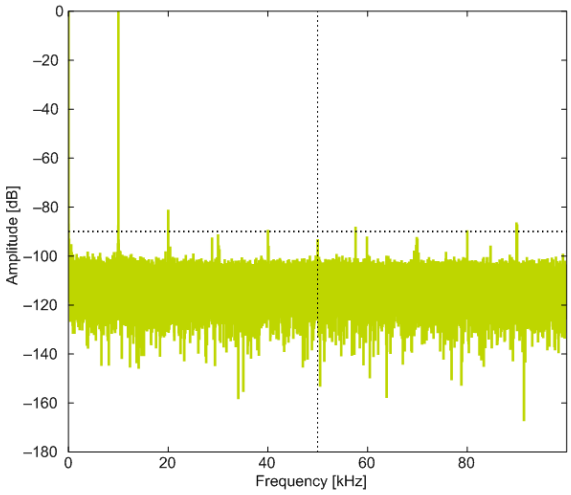



***Figure 3.25. Differential Non-Linearity (DNL)***

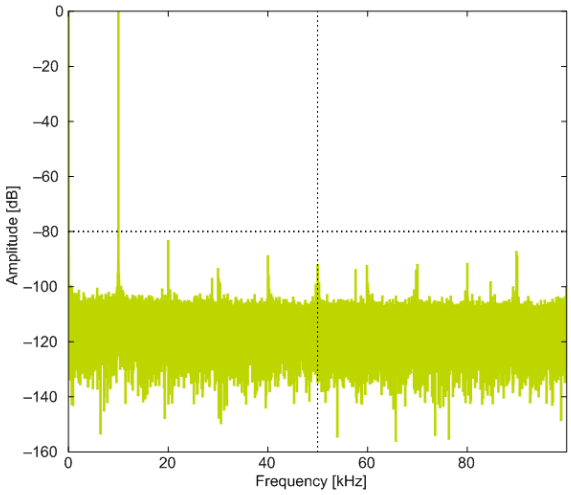


## 3.10.1 Typical performance

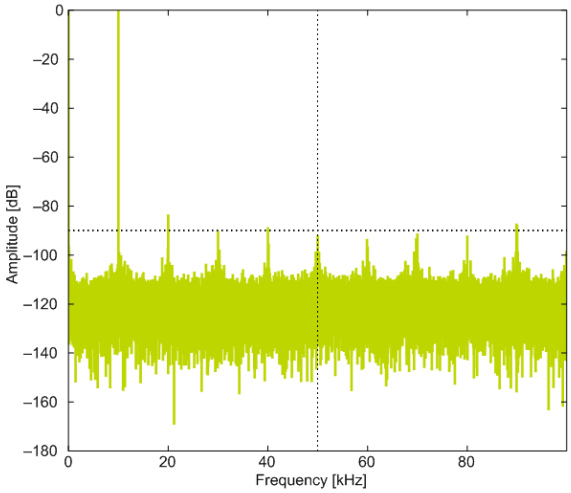
***Figure 3.26. ADC Frequency Spectrum, Vdd = 3V, Temp = 25°C***



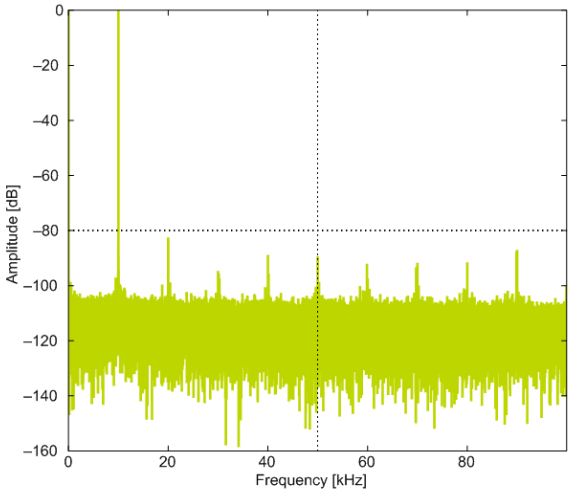

1.25V Reference



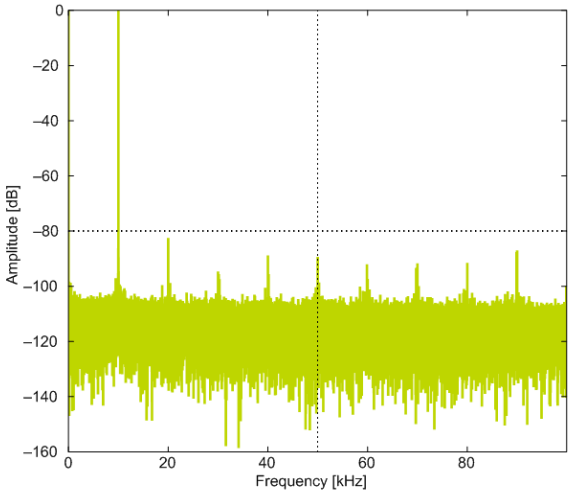

2.5V Reference




2XVDDVSS Reference

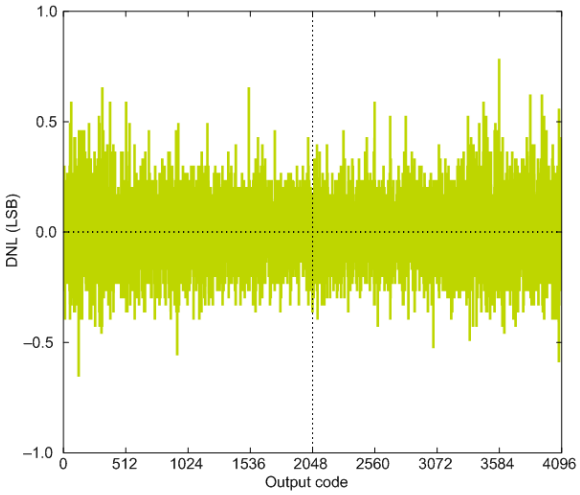



5VDIFF Reference

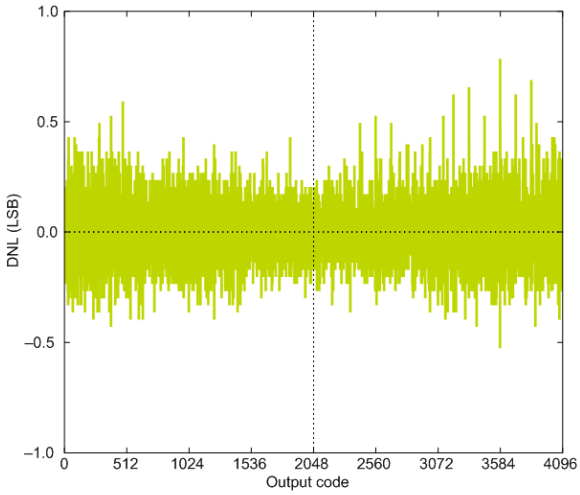



VDD Reference

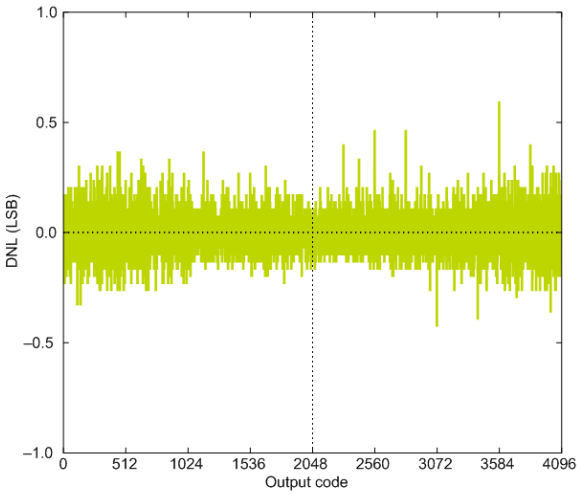
***Figure 3.28. ADC Differential Linearity Error vs Code, Vdd = 3V, Temp = 25°C***



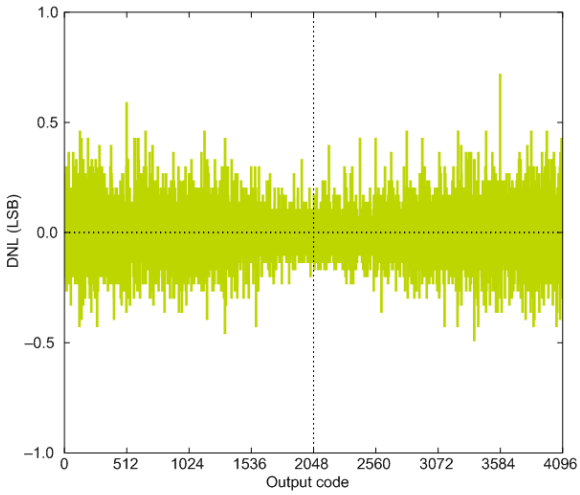

1.25V Reference



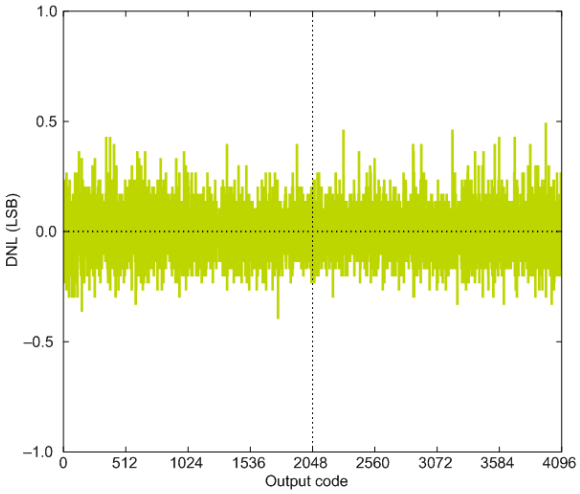

2.5V Reference




2XVDDVSS Reference

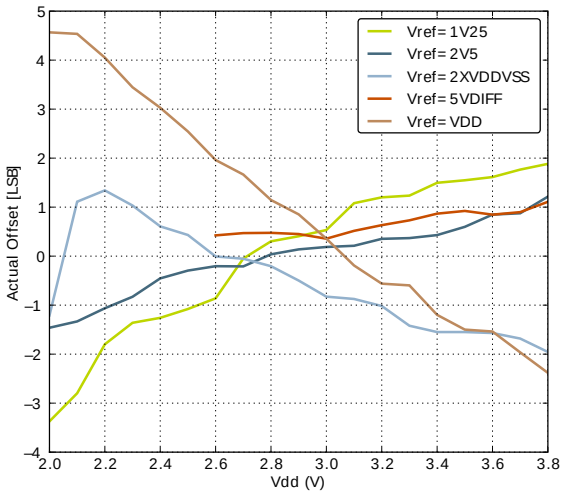



5VDIFF Reference

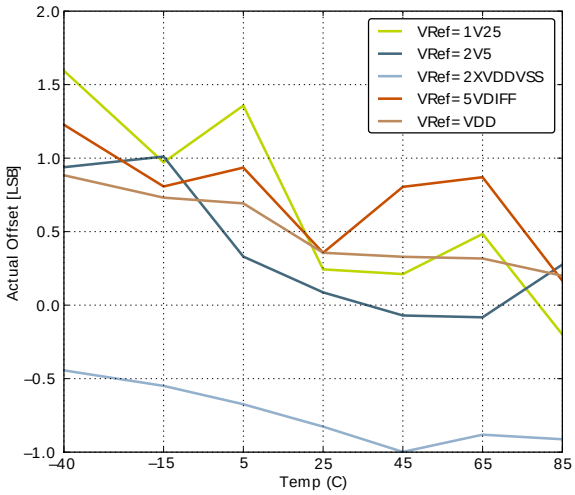



VDD Reference

***Figure 3.29. ADC Absolute Offset, Common Mode = Vdd /2***

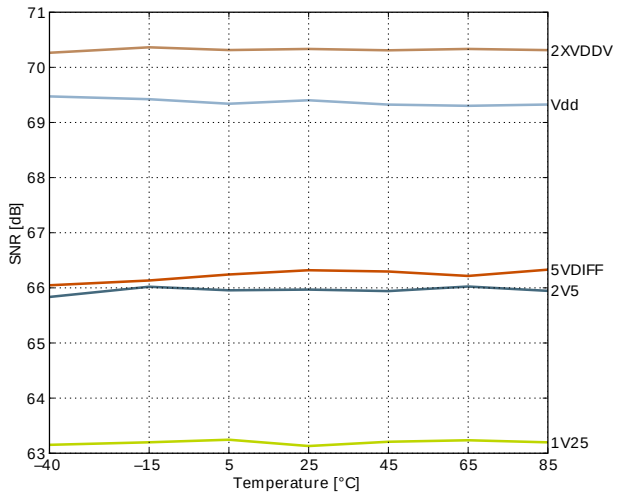



Offset vs Supply Voltage, Temp = 25°C

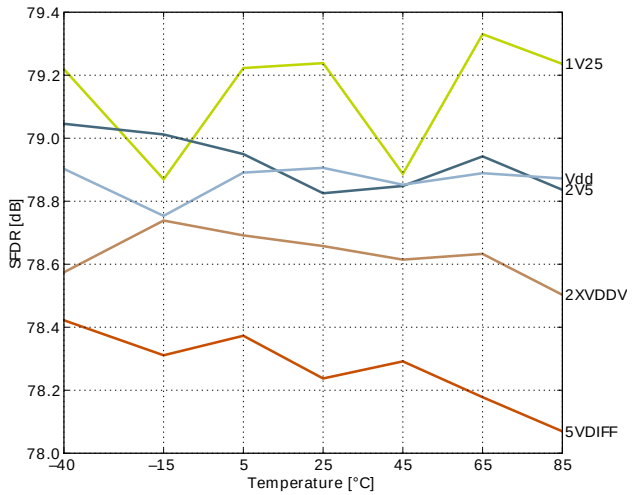



Offset vs Temperature, Vdd = 3V

***Figure 3.30. ADC Dynamic Performance vs Temperature for all ADC References, Vdd = 3V***

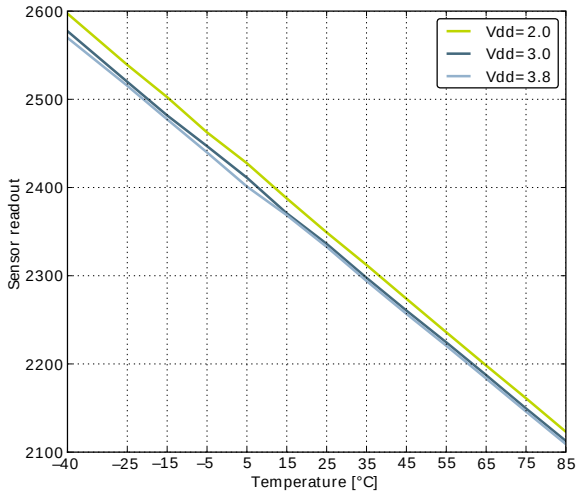



Signal to Noise Ratio (SNR)




Spurious-Free Dynamic Range (SFDR)

***Figure 3.31. ADC Temperature sensor readout***




# 3.11 Digital Analog Converter (DAC)

***Table 3.16. DAC***

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{DACOUT}$ | Output voltage range | VDD voltage reference, single ended | 0 | | $V_{DD}$ | V |
| | | VDD voltage reference, differential | $-V_{DD}$ | | $V_{DD}$ | V |
| $V_{DACCM}$ | Output common mode voltage range | | 0 | | $V_{DD}$ | V |
| $I_{DAC}$ | Active current including references for 2 channels | 500 kSamples/s, 12 bit | | 400[1] | | µA |
| | | 100 kSamples/s, 12 bit | | 200[1] | | µA |
| | | 1 kSamples/s 12 bit NORMAL | | 17[1] | | µA |
| $SR_{DAC}$ | Sample rate | | | | 500 | ksamples/s |
| $f_{DAC}$ | DAC clock frequency | Continuous Mode | | | 1000 | kHz |
| | | Sample/Hold Mode | | | 250 | kHz |
| | | Sample/Off Mode | | | 250 | kHz |
| $CYC_{DACCONV}$ | Clock cyckles per conversion | | | 2 | | |
| $t_{DACCONV}$ | Conversion time | | 2 | | | µs |
| $t_{DACSETTLE}$ | Settling time | | | 5 | | µs |
| $SNR_{DAC}$ | Signal to Noise Ratio (SNR) | 500 kSamples/s, 12 bit, single ended, internal 1.25V reference | | 58 | | dB |
| | | 500 kSamples/s, 12 bit, single ended, internal 2.5V reference | | 59 | | dB |
| | | 500 kSamples/s, 12 bit, differential, internal 1.25V reference | | 58 | | dB |

# 3.13 Analog Comparator (ACMP)

***Table 3.18. ACMP***

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{ACMPIN}$ | Input voltage range | | 0 | | $V_{DD}$ | V |
| $V_{ACMPCM}$ | ACMP Common Mode voltage range | | 0 | | $V_{DD}$ | V |
| $I_{ACMP}$ | Active current | BIASPROG=0b0000, FULLBIAS=0 and HALFBIAS=1 in ACMPn_CTRL register | | 0.1 | 0.4 | µA |
| | | BIASPROG=0b1111, FULLBIAS=0 and HALFBIAS=0 in ACMPn_CTRL register | | 2.87 | 15 | µA |
| | | BIASPROG=0b1111, FULLBIAS=1 and HALFBIAS=0 in ACMPn_CTRL register | | 195 | 520 | µA |
| $I_{ACMPREF}$ | Current consumption of internal voltage reference | Internal voltage reference off. Using external voltage reference | | 0 | | µA |
| | | Internal voltage reference | | 5 | | µA |
| $V_{ACMPOFFSET}$ | Offset voltage | BIASPROG= 0b1010, FULLBIAS=0 and HALFBIAS=0 in ACMPn_CTRL register | -12 | 0 | 12 | mV |
| $V_{ACMPHYST}$ | ACMP hysteresis | Programmable | | 17 | | mV |
| $R_{CSRES}$ | Capacitive Sense Internal Resistance | CSRESSEL=0b00 in ACMPn_INPUTSEL | | 39 | | kOhm |
| | | CSRESSEL=0b01 in ACMPn_INPUTSEL | | 71 | | kOhm |
| | | CSRESSEL=0b10 in ACMPn_INPUTSEL | | 104 | | kOhm |
| | | CSRESSEL=0b11 in ACMPn_INPUTSEL | | 136 | | kOhm |
| $t_{ACMPSTART}$ | Startup time | | | | 10 | µs |

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given in Equation 3.1 (p. 47) . $I_{ACMPREF}$ is zero if an external voltage reference is used.

***Total ACMP Active Current***

$$I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF} \quad (3.1)$$

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{SCLK\_MI}$ [1][2] | SCLK to MISO | -264 + $t_{HF-PERCLK}$ | | -234 + 2 * $t_{HFPERCLK}$ | ns |

[1]Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)
[2]Measurement done at 10% and 90% of $V_{DD}$ (figure shows 50% of $_{VDD}$)

# 3.17 Digital Peripherals

***Table 3.27. Digital Peripherals***

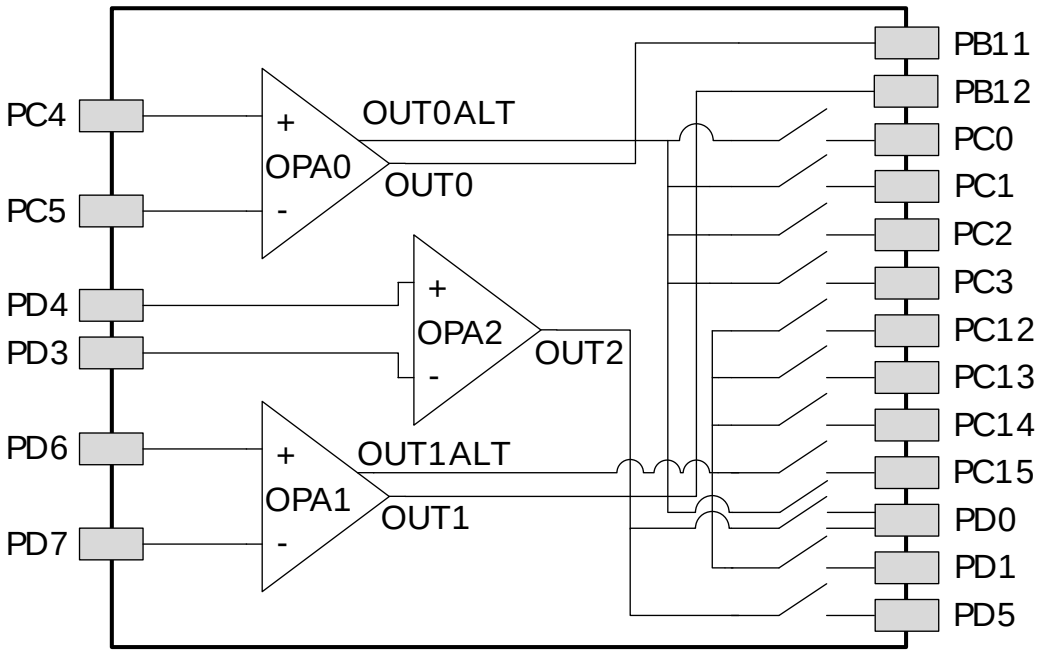
| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $I_{USART}$ | USART current | USART idle current, clock enabled | | 4.0 | | µA/MHz |
| $I_{UART}$ | UART current | UART idle current, clock enabled | | 3.8 | | µA/MHz |
| $I_{LEUART}$ | LEUART current | LEUART idle current, clock enabled | | 194.0 | | nA |
| $I_{I2C}$ | I2C current | I2C idle current, clock enabled | | 7.6 | | µA/MHz |
| $I_{TIMER}$ | TIMER current | TIMER_0 idle current, clock enabled | | 6.5 | | µA/MHz |
| $I_{LETIMER}$ | LETIMER current | LETIMER idle current, clock enabled | | 85.8 | | nA |
| $I_{PCNT}$ | PCNT current | PCNT idle current, clock enabled | | 91.4 | | nA |
| $I_{RTC}$ | RTC current | RTC idle current, clock enabled | | 54.6 | | nA |
| $I_{AES}$ | AES current | AES idle current, clock enabled | | 1.8 | | µA/MHz |
| $I_{GPIO}$ | GPIO current | GPIO idle current, clock enabled | | 3.4 | | µA/MHz |
| $I_{PRS}$ | PRS current | PRS idle current | | 3.9 | | µA/MHz |
| $I_{DMA}$ | DMA current | Clock enable | | 10.9 | | µA/MHz |

| QFN64 Pin# and Name | | Pin Alternate Functionality / Description | | | |
|---|---|---|---|---|---|
| Pin # | Pin Name | Analog | Timers | Communication | Other |
| 3 | PA2 | | TIM0_CC2 #0/1 | | CMU_CLK0 #0<br>ETM_TD0 #3 |
| 4 | PA3 | | TIM0_CDTI0 #0 | | LES_ALTEX2 #0<br>ETM_TD1 #3 |
| 5 | PA4 | | TIM0_CDTI1 #0 | | LES_ALTEX3 #0<br>ETM_TD2 #3 |
| 6 | PA5 | | TIM0_CDTI2 #0 | LEU1_TX #1 | LES_ALTEX4 #0<br>ETM_TD3 #3 |
| 7 | PA6 | | | LEU1_RX #1 | ETM_TCLK #3<br>GPIO_EM4WU1 |
| 8 | IOVDD_0 | Digital IO power supply 0. | | | |
| 9 | PC0 | ACMP0_CH0<br>DAC0_OUT0ALT #0/<br>OPAMP_OUT0ALT | TIM0_CC1 #4<br>PCNT0_S0IN #2 | US0_TX #5<br>US1_TX #0<br>I2C0_SDA #4 | LES_CH0 #0<br>PRS_CH2 #0 |
| 10 | PC1 | ACMP0_CH1<br>DAC0_OUT0ALT #1/<br>OPAMP_OUT0ALT | TIM0_CC2 #4<br>PCNT0_S1IN #2 | US0_RX #5<br>US1_RX #0<br>I2C0_SCL #4 | LES_CH1 #0<br>PRS_CH3 #0 |
| 11 | PC2 | ACMP0_CH2<br>DAC0_OUT0ALT #2/<br>OPAMP_OUT0ALT | TIM0_CDTI0 #4 | US2_TX #0 | LES_CH2 #0 |
| 12 | PC3 | ACMP0_CH3<br>DAC0_OUT0ALT #3/<br>OPAMP_OUT0ALT | TIM0_CDTI1 #4 | US2_RX #0 | LES_CH3 #0 |
| 13 | PC4 | ACMP0_CH4<br>DAC0_P0 /<br>OPAMP_P0 | TIM0_CDTI2 #4<br>LETIM0_OUT0 #3<br>PCNT1_S0IN #0 | US2_CLK #0<br>I2C1_SDA #0 | LES_CH4 #0 |
| 14 | PC5 | ACMP0_CH5<br>DAC0_N0 /<br>OPAMP_N0 | LETIM0_OUT1 #3<br>PCNT1_S1IN #0 | US2_CS #0<br>I2C1_SCL #0 | LES_CH5 #0 |
| 15 | PB7 | LFXTAL_P | TIM1_CC0 #3 | US0_TX #4<br>US1_CLK #0 | |
| 16 | PB8 | LFXTAL_N | TIM1_CC1 #3 | US0_RX #4<br>US1_CS #0 | |
| 17 | PA8 | | TIM2_CC0 #0 | | |
| 18 | PA9 | | TIM2_CC1 #0 | | |
| 19 | PA10 | | TIM2_CC2 #0 | | |
| 20 | RESETn | Reset input, active low.<br>To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released. | | | |
| 21 | PB11 | DAC0_OUT0 /<br>OPAMP_OUT0 | TIM1_CC2 #3<br>LETIM0_OUT0 #1 | I2C1_SDA #1 | |
| 22 | PB12 | DAC0_OUT1 /<br>OPAMP_OUT1 | LETIM0_OUT1 #1 | I2C1_SCL #1 | |
| 23 | AVDD_1 | Analog power supply 1. | | | |
| 24 | PB13 | HFXTAL_P | | US0_CLK #4/5<br>LEU0_TX #1 | |
| 25 | PB14 | HFXTAL_N | | US0_CS #4/5<br>LEU0_RX #1 | |
| 26 | IOVDD_3 | Digital IO power supply 3. | | | |
| 27 | AVDD_0 | Analog power supply 0. | | | |
| 28 | PD0 | ADC0_CH0<br>DAC0_OUT0ALT #4/<br>OPAMP_OUT0ALT | PCNT2_S0IN #0 | US1_TX #1 | |

| Alternate | LOCATION | | | | | | | |
|---|---|---|---|---|---|---|---|---|
| Functionality | 0 | 1 | 2 | 3 | 4 | 5 | 6 | Description |
| ADC0_CH2 | PD2 | | | | | | | Analog to digital converter ADC0, input channel number 2. |
| ADC0_CH3 | PD3 | | | | | | | Analog to digital converter ADC0, input channel number 3. |
| ADC0_CH4 | PD4 | | | | | | | Analog to digital converter ADC0, input channel number 4. |
| ADC0_CH5 | PD5 | | | | | | | Analog to digital converter ADC0, input channel number 5. |
| ADC0_CH6 | PD6 | | | | | | | Analog to digital converter ADC0, input channel number 6. |
| ADC0_CH7 | PD7 | | | | | | | Analog to digital converter ADC0, input channel number 7. |
| BOOT_RX | PE11 | | | | | | | Bootloader RX |
| BOOT_TX | PE10 | | | | | | | Bootloader TX |
| BU_VIN | PD8 | | | | | | | Battery input for Backup Power Domain |
| CMU_CLK0 | PA2 | | PD7 | | | | | Clock Management Unit, clock output number 0. |
| CMU_CLK1 | PA1 | PD8 | PE12 | | | | | Clock Management Unit, clock output number 1. |
| DAC0_N0 / OPAMP_N0 | PC5 | | | | | | | Operational Amplifier 0 external negative input. |
| DAC0_N1 / OPAMP_N1 | PD7 | | | | | | | Operational Amplifier 1 external negative input. |
| OPAMP_N2 | PD3 | | | | | | | Operational Amplifier 2 external negative input. |
| DAC0_OUT0 / OPAMP_OUT0 | PB11 | | | | | | | Digital to Analog Converter DAC0_OUT0 / OPAMP output channel number 0. |
| DAC0_OUT0ALT / OPAMP_OUT0ALT | PC0 | PC1 | PC2 | PC3 | PD0 | | | Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0. |
| DAC0_OUT1 / OPAMP_OUT1 | PB12 | | | | | | | Digital to Analog Converter DAC0_OUT1 / OPAMP output channel number 1. |
| DAC0_OUT1ALT / OPAMP_OUT1ALT | | | | | PD1 | | | Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1. |
| OPAMP_OUT2 | PD5 | PD0 | | | | | | Operational Amplifier 2 output. |
| DAC0_P0 / OPAMP_P0 | PC4 | | | | | | | Operational Amplifier 0 external positive input. |
| DAC0_P1 / OPAMP_P1 | PD6 | | | | | | | Operational Amplifier 1 external positive input. |
| OPAMP_P2 | PD4 | | | | | | | Operational Amplifier 2 external positive input. |
| DBG_SWCLK | PF0 | PF0 | PF0 | PF0 | | | | Debug-interface Serial Wire clock input.<br>Note that this function is enabled to pin out of reset, and has a built-in pull down. |
| DBG_SWDIO | PF1 | PF1 | PF1 | PF1 | | | | Debug-interface Serial Wire data input / output.<br>Note that this function is enabled to pin out of reset, and has a built-in pull up. |
| DBG_SWO | PF2 | | PD1 | PD2 | | | | Debug-interface Serial Wire viewer Output.<br>Note that this function is not enabled after reset, and must be enabled by software to be used. |
| ETM_TCLK | PD7 | | PC6 | PA6 | | | | Embedded Trace Module ETM clock . |
| ETM_TD0 | PD6 | | PC7 | PA2 | | | | Embedded Trace Module ETM data 0. |
| ETM_TD1 | PD3 | | PD3 | PA3 | | | | Embedded Trace Module ETM data 1. |
| ETM_TD2 | PD4 | | PD4 | PA4 | | | | Embedded Trace Module ETM data 2. |
| ETM_TD3 | PD5 | | PD5 | PA5 | | | | Embedded Trace Module ETM data 3. |
| GPIO_EM4WU0 | PA0 | | | | | | | Pin can be used to wake the system up from EM4 |
| GPIO_EM4WU1 | PA6 | | | | | | | Pin can be used to wake the system up from EM4 |
| GPIO_EM4WU2 | PC9 | | | | | | | Pin can be used to wake the system up from EM4 |

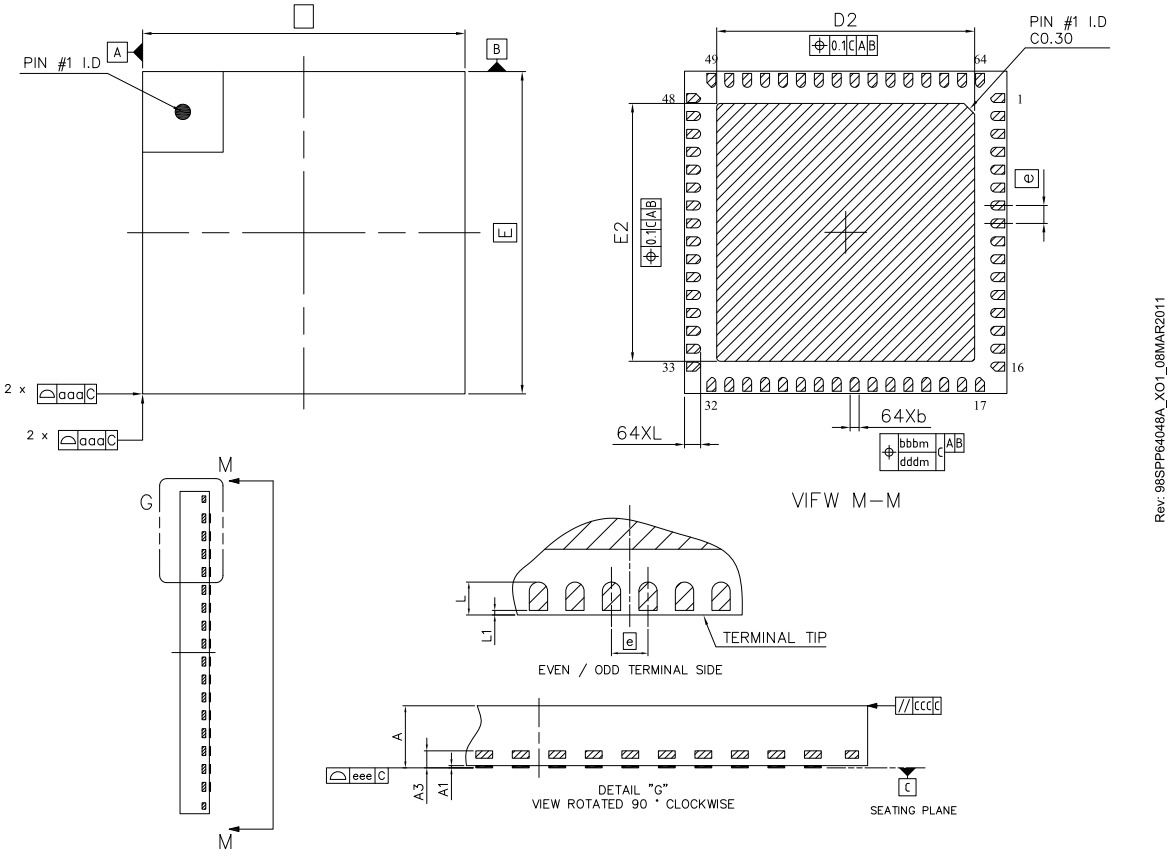
| Alternate | LOCATION | | | | | | | |
|---|---|---|---|---|---|---|---|---|
| Functionality | 0 | 1 | 2 | 3 | 4 | 5 | 6 | Description |
| PCNT1_S0IN | PC4 | | | | | | | Pulse Counter PCNT1 input number 0. |
| PCNT1_S1IN | PC5 | | | | | | | Pulse Counter PCNT1 input number 1. |
| PCNT2_S0IN | PD0 | PE8 | | | | | | Pulse Counter PCNT2 input number 0. |
| PCNT2_S1IN | PD1 | PE9 | | | | | | Pulse Counter PCNT2 input number 1. |
| PRS_CH0 | PA0 | | | | | | | Peripheral Reflex System PRS, channel 0. |
| PRS_CH1 | PA1 | | | | | | | Peripheral Reflex System PRS, channel 1. |
| PRS_CH2 | PC0 | PF5 | | | | | | Peripheral Reflex System PRS, channel 2. |
| PRS_CH3 | PC1 | PE8 | | | | | | Peripheral Reflex System PRS, channel 3. |
| TIM0_CC0 | PA0 | PA0 | | PD1 | PA0 | PF0 | | Timer 0 Capture Compare input / output channel 0. |
| TIM0_CC1 | PA1 | PA1 | | PD2 | PC0 | PF1 | | Timer 0 Capture Compare input / output channel 1. |
| TIM0_CC2 | PA2 | PA2 | | PD3 | PC1 | PF2 | | Timer 0 Capture Compare input / output channel 2. |
| TIM0_CDTI0 | PA3 | | | | PC2 | | | Timer 0 Complimentary Deat Time Insertion channel 0. |
| TIM0_CDTI1 | PA4 | | | | PC3 | | | Timer 0 Complimentary Deat Time Insertion channel 1. |
| TIM0_CDTI2 | PA5 | | PF5 | | PC4 | PF5 | | Timer 0 Complimentary Deat Time Insertion channel 2. |
| TIM1_CC0 | | PE10 | | PB7 | PD6 | | | Timer 1 Capture Compare input / output channel 0. |
| TIM1_CC1 | | PE11 | | PB8 | PD7 | | | Timer 1 Capture Compare input / output channel 1. |
| TIM1_CC2 | | PE12 | | PB11 | | | | Timer 1 Capture Compare input / output channel 2. |
| TIM2_CC0 | PA8 | | PC8 | | | | | Timer 2 Capture Compare input / output channel 0. |
| TIM2_CC1 | PA9 | | PC9 | | | | | Timer 2 Capture Compare input / output channel 1. |
| TIM2_CC2 | PA10 | | PC10 | | | | | Timer 2 Capture Compare input / output channel 2. |
| TIM3_CC0 | PE14 | | | | | | | Timer 3 Capture Compare input / output channel 0. |
| TIM3_CC1 | PE15 | | | | | | | Timer 3 Capture Compare input / output channel 1. |
| TIM3_CC2 | PA15 | | | | | | | Timer 3 Capture Compare input / output channel 2. |
| US0_CLK | PE12 | | PC9 | | PB13 | PB13 | | USART0 clock input / output. |
| US0_CS | PE13 | | PC8 | | PB14 | PB14 | | USART0 chip select input / output. |
| US0_RX | PE11 | | PC10 | PE12 | PB8 | PC1 | | USART0 Asynchronous Receive.<br>USART0 Synchronous mode Master Input / Slave Output (MISO). |
| US0_TX | PE10 | | PC11 | PE13 | PB7 | PC0 | | USART0 Asynchronous Transmit.Also used as receive input in half duplex communication.<br>USART0 Synchronous mode Master Output / Slave Input (MOSI). |
| US1_CLK | PB7 | PD2 | PF0 | | | | | USART1 clock input / output. |
| US1_CS | PB8 | PD3 | PF1 | | | | | USART1 chip select input / output. |
| US1_RX | PC1 | PD1 | PD6 | | | | | USART1 Asynchronous Receive.<br>USART1 Synchronous mode Master Input / Slave Output (MISO). |
| US1_TX | PC0 | PD0 | PD7 | | | | | USART1 Asynchronous Transmit.Also used as receive input in half duplex communication.<br>USART1 Synchronous mode Master Output / Slave Input (MOSI). |
| US2_CLK | PC4 | | | | | | | USART2 clock input / output. |
| US2_CS | PC5 | | | | | | | USART2 chip select input / output. |
| US2_RX | PC3 | | | | | | | USART2 Asynchronous Receive. |

***Figure 4.2. Opamp Pinout***




## 4.5 QFN64 Package

***Figure 4.3. QFN64***




Note:

1. Dimensioning & tolerancing confirm to ASME Y14.5M-1994.
2. All dimensions are in millimeters. Angles are in degrees.

3. Dimension 'b' applies to metallized terminal and is measured between 0.25 mm and 0.30 mm from the terminal tip. Dimension L1 represents terminal full back from package edge up to 0.1 mm is acceptable.
4. Coplanarity applies to the exposed heat slug as well as the terminal.
5. Radius on terminal is optional

***Table 4.4. QFN64 (Dimensions in mm)***

| Symbol | A | A1 | A3 | b | D | E | D2 | E2 | e | L | L1 | aaa | bbb | ccc | ddd | eee |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Min | 0.80 | 0.00 | | 0.20 | | | 7.10 | 7.10 | | 0.40 | 0.00 | | | | | |
| Nom | 0.85 | - | 0.203 REF | 0.25 | 9.00 BSC | 9.00 BSC | 7.20 | 7.20 | 0.50 BSC | 0.45 | | 0.10 | 0.10 | 0.10 | 0.05 | 0.08 |
| Max | 0.90 | 0.05 | | 0.30 | | | 7.30 | 7.30 | | 0.50 | 0.10 | | | | | |

The QFN64 Package uses Nickel-Palladium-Gold preplated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see:
http://www.silabs.com/support/quality/pages/default.aspx